PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7363540

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHEN-FU CHU	05/26/2022
SHIH-KAI CHAN	05/26/2022
YI-FENG SHIH	05/26/2022
DAVID TRUNG DOAN	05/26/2022
TRUNG TRI DOAN	05/26/2022
YOSHINORI OGAWA	05/26/2022
KOHEI OTAKE	05/27/2022
KAZUNORI KONDO	05/27/2022
KEIJI OHORI	05/27/2022
TAICHI KITAGAWA	05/27/2022
NOBUAKI MATSUMOTO	05/29/2022
TOSHIYUKI OZAI	05/27/2022
SHUHEI UEDA	05/27/2022

RECEIVING PARTY DATA

Name:	SEMILEDS CORPORATION
Street Address:	1F, NO. 11, KE JUNG RD., CHU-NAN SITE
Internal Address:	HSINCHU SCIENCE PARK
City:	CHU-NAN, MIAO-LI COUNTY
State/Country:	TAIWAN
Postal Code:	350
Name:	SHIN-ETSU CHEMICAL CO., LTD.
Street Address:	20TH FLOOR, MARUNOUCHI EIRAKU BLDG.,
Internal Address:	4-1, MARUNOUCHI 1-CHOME, CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	100-0005

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17740729

CORRESPONDENCE DATA

Fax Number: (303)989-6353

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3039896353

Email: steve@grattonlaw.com

Correspondent Name: STEPHEN A. GRATTON

Address Line 1: 2764 SOUTH BRAUN WAY

Address Line 4: LAKEWOOD, COLORADO 80228

ATTORNEY DOCKET NUMBER:	TSLC/SHINETSU2019-002.01C
NAME OF SUBMITTER:	STEPHEN A. GRATTON
SIGNATURE:	/STEPHEN A. GRATTON/
DATE SIGNED:	06/03/2022

Total Attachments: 14

source=TSLCSHINETSU201900201assign#page1.tif
source=TSLCSHINETSU201900201assign#page2.tif
source=TSLCSHINETSU201900201assign#page3.tif
source=TSLCSHINETSU201900201assign#page4.tif
source=TSLCSHINETSU201900201assign#page5.tif
source=TSLCSHINETSU201900201assign#page6.tif
source=TSLCSHINETSU201900201assign#page7.tif
source=TSLCSHINETSU201900201assign#page8.tif
source=TSLCSHINETSU201900201assign#page9.tif
source=TSLCSHINETSU201900201assign#page10.tif
source=TSLCSHINETSU201900201assign#page11.tif
source=TSLCSHINETSU201900201assign#page12.tif
source=TSLCSHINETSU201900201assign#page13.tif
source=TSLCSHINETSU201900201assign#page14.tif

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

CHEN-FU CHU
SHIH-KAI CHAN
YI-FENG SHIH
DAVID TRUNG DOAN
TRUNG TRI DOAN
YOSHINORI OGAWA
KOHEI OTAKE
KAZUNORI KONDO
KEIJI OHORI
TAICHI KITAGAWA
NOBUAKI MATSUMOTO
TOSHIYUKI OZAI
SHUHEI UEDA

Serial No.: 17/740,729

Filing Date: 05/10/2022

Title: **METHOD FOR FABRICATING (LED) DICE USING SEMICONDUCTOR STRUCTURES ON A SUBSTRATE AND A LASER LIFT-OFF TO A RECEIVING PLATE**

Docket No. TSLC&SHIN-ETSU/2019-002.01C/US

ASSIGNMENT:

_x_ Enclosed for recording
___ Previously recorded
Date: ____________________
Reel: ____________________

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency, and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN, AND TRANSFER to SemiLEDs Corporation a Delaware corporation, with its business address at 1F, No. 11, Ke Jung Rd., Chu-Nan Site, Hsinchu Science Park, Chu-nan 350, Miao-Li County, Taiwan, R.O.C. and SHIN-ETSU CHEMICAL CO., LTD., a Japanese company with its business address at 20th Floor (Reception), Marunouchi Eiraku Bldg., 4-1, Marunouchi 1-chome, Chiyoda-ku,Tokyo

100-0005, Japan (the "Assignees), the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which will be executed by the undersigned and is entitled **METHOD FOR FABRICATING (LED) DICE USING SEMICONDUCTOR STRUCTURES ON A SUBSTRATE AND LASER LIFT-OFF TO A RECEIVING PLATE;** such application and all divisional, continuing, substitute, renewal, reissue, and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America:

AUTHORIZE AND REQUEST, the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney, and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining, and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives, and successors of the undersigned and extend to the successors, assigns, and nominees of the Assignee.

Signature:

Chen-Fu Chu Date 2022/5/26
CHEN-FU CHU

Signature:

Shih-Kai Chan Date 2022. 5. 26

SHIH-KAI CHAN

PATENT
REEL: 060269 FRAME: 0715

Signature:

YI-FENG SHIH Date 2022.05.26

YI-FENG SHIH

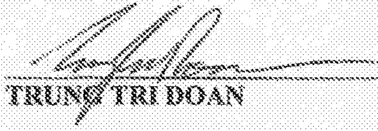
PATENT
REEL: 060269 FRAME: 0716

Signature:

Date 2022-05-26

DAVID TRUNG DOAN

Signature:



_________________________ Date 2022-05-26

TRUNG TRI DOAN

PATENT
REEL: 060269 FRAME: 0718

Signature:

Date May 26, 2022

YOSHINORI OGAWA

Signature:

Kohei Otake Date May 27, 2022

KOHEI OTAKE

PATENT
REEL: 060269 FRAME: 0720

Signature:

Kazunori Kondo Date May 29, 2022

KAZUNORI KONDO

Signature:

K. Ohori Date May. 27. 2022

KEIJI OHORI

Signature:

Taichi Kitagawa Date May. 27. 2022
TAICHI KITAGAWA

Signature:

Nobuaki Matsumoto Date May. 29, 2022

NOBUAKI MATSUMOTO

PATENT
REEL: 060269 FRAME: 0724

Signature:

Toshiyuki Ozai Date May. 27. 2022
TOSHIYUKI OZAI

Signature:

Shuhei Ueda Date May. 27th, 2022
SHUHEI UEDA

PATENT
RECORDED: 06/03/2022 REEL: 060269 FRAME: 0726